

Factory Automation Solutions

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What Sets Apacer Apart?

Professional Technique

- Strong HW/FW engineering know-how
- Customized design with a variety of solutions
- State-of-the-art technology

Quality Assurance

• 100% reliable & compliant

Wide temperature test Thermal shock test Strict ORT (Ongoing Reliability Test) Humidity test Altitude test

Reliability test (Vibration/Shock)

Extensive Experience

- Tier 1 industrial SSD & memory supplier; delivered over 135 million units
- Comprehensive experience in product customization (across industries)

S CONSISTENTLY PRINKED

INDUSTRIAL SSD SUPPLIER GARTNER

Reliable Service

- Fixed BOM solution
- Longevity of supply, EOL & LTB notice
- Manufacturing in Taiwan protects IP

Trustworthy Supplier

- A global-scale service and maintenance system
- Responsive local FAE technical support
- 24/7 flexible and quick delivery service
- Complete RMA system

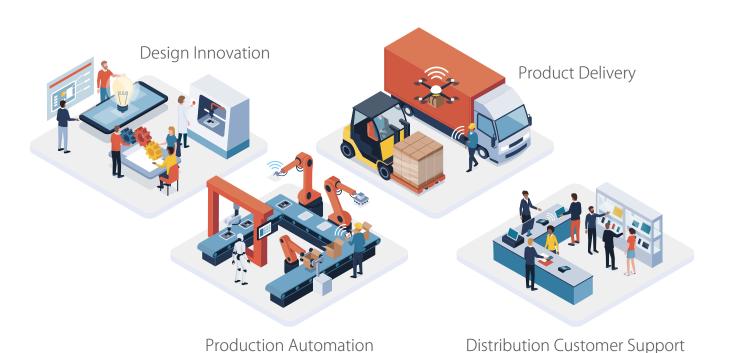
Challenges and Requirements for Factory Automation Applications

The ever-rising cost of labor has become a key concern for manufacturers, especially in the last few decades. Now, as computer-controlled robotics finally come into their own, manufacturers are looking for fast and reliable ways to automate part or all of their manufacturing. The challenge is data – the more production steps that are automated, the more data needs to be collected and analyzed.

Apacer, as a leading industrial manufacturer, is one of the few companies with the experience base required to develop solutions for factory automation. Data integrity is paramount, but it can't come at the sacrifice of speed, because the amount of data being generated is rising so quickly. Apacer's DRAM modules and SSDs deliver the combination of speed and reliability that top manufacturers demand.

In this brochure, we'll take a deeper dive into Apacer's value-adding technologies and reveal how they can help with the coming transfer to full factory automation.

Factory Automation Applications





Challenges and Requirements

Since data gathering and analysis is necessary for constant improvement, the automation industry demands excellent data integrity. Apacer delivers this in spades, thanks to advanced algorithms like DataRAID™, carefully tweaked by our experienced software engineers. Endurance and power stability are also concerns, but again, these are areas in which Apacer's technology excels. Over-provisioning helps extend operational lifetimes, while DataDefender™ prevents data corruption that can occur when power fails unexpectedly. For factories where sulfur or contaminants pollute the air, Apacer offers resistant coatings and patented anti-sulfuration protection. And all the while, the smooth operation of the production facility can be monitored remotely thanks to Apacer's Double-barreled Solution.

Featured Technologies for Factory Automation Applications

Data Integrity DataRAID™ · End-to-end Data · Smart Read Refresh Protection









Data Integrity



SIGNAT Read Refresh[™]

Apacer Smart Read Refresh[™] plays a proactive role in avoiding read disturb errors from occurring to ensure the health status of all blocks of NAND flash. Developed for read-intensive applications in particular, Smart Read Refresh[™] is employed to make sure that during read operations, when the read operation threshold is reached, the data is refreshed by re-writing it to a different block for subsequent use.



Data Retention

Data retention refers to how long stored data can be maintained while a storage device is powered down. Apacer offers a number of optimization strategies to help customers achieve the ideal balance of data retention with P/E cycles for industrial applications.



End-to-end Data Protection

Apacer's End-to-end Data Protection is a feature implemented in Apacer SSD products that extends error control to cover the entire path from the host computer to the drive and back, and ensure data integrity at multiple points in the path through error-checking techniques including CRC, ECC and DataRAID $^{\text{IM}}$ to enable reliable data transfer.

C Longevity



Over-provisioning

To reduce write amplification and increase endurance and performance, Apacer's SSDs support over-provisioning. The SSDs set aside a certain portion of the physical capacity of the memory to carry out garbage collection, wear-leveling and bad block mapping operations. The end result is a longer operating lifetime for our SSDs.



SLC-lite

SLC-lite is Apacer's proprietary technology that strikes a cost-performance balance between MLC and SLC flash types, making it an ideal alternative solution for mission-critical embedded or industrial applications.



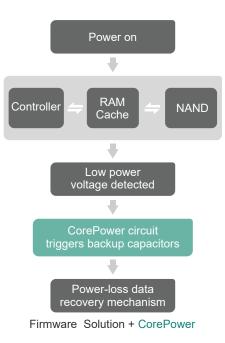
🏵 Power Stability



Data Derender **

Apacer DataDefender™ combines both firmware and hardware mechanisms to ensure data integrity.

When power disruption occurs, the hardware mechanism will notice and trigger the controller to run multiple write-to-flash cycles to store data. Then the firmware will check that the data was correctly written to the NAND flash after the power disruption, preventing data loss.





CorePower

Apacer's hardware-based technology is designed to prevent data loss and ensure the stability of data transmission during a power outage by implementing a backup power supply that allows sufficient time to move all cached data to NAND flash.



Detect



Backup Power

- SSD will stop receiving host commands
- Detect IC will inform controller to move all the cached data into NAND
- Capacitors start working backup power supply





🚵 Survivability



Wide Temperature

Apacer insists on using industrial-grade chips from original manufacturers to ensure operation reliability in extreme temperatures ranging from -40°C to 85°C.



Dust/Moisture



Conformal Coating

Enhances reliability of products by applying coatings on the surface of printed circuit boards. The protective film can safeguard devices from dust ingression and liquid immersion.

- Uses automated spraying to maintain precise coating thickness
- Enhances product reliability
- Prolongs SSD and DRAM modules' lifespan



Nano Coating

The IP57 waterproof and dustproof Nano Coating (parylene coating) solution is especially ideal for SSD modules as it provides invulnerable protection for the components on the devices.

| | Conformal Coating | Nano Coating | |
|---------------|-----------------------------------|---|--|
| Protection | Dust, moisture, fungus, corrosion | Dust, moisture, fungus, corrosion IP57 | |
| Cost | \$ | \$\$\$ | |
| Additional LT | 14 Working-days | 14 Working-days | |



Underfill

Apacer provides underfill technology to increase product reliability and resistance to various thermal and mechanical shocks.

- · Strengthens the solder joints between solder balls and printed circuit board
- Increases the product's resistance against shock and vibration
- · Reduces thermal stress damage
- · Complies with MIL-STD-810G shock and vibration requirements
- · Increases product reliability and lifespan





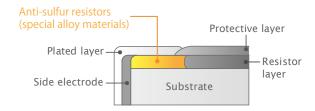
Anti-sulfuration

Anti-sulfuration memory modules are mainly used in equipment exposed to a highly contaminated environment.

- · World's first anti-sulfuration memory modules
- Solve corrosion problems effectively and increase overall system lifespan
- · Ensure product reliability and durability

Apacer's anti-sulfuration technology

Resistor construction



Apacer has been awarded patents for its anti-sulfuration memory, which prevents sulfur corrosion problems.

Widely recognized and awarded patents

| 2 | No. |
|-----------|----------------|
| 2019/3/1 | 201610348460.2 |
| 2017/4/11 | US9,622,337 |
| 2017/9/11 | 1598878 |
| | 2017/4/11 |

Value-added Application

Double-barreled Solution



Apacer's Double-barreled Solution extends SSD lifespans, and is comprised of CoreAnalyzer2 and SSDWidget 2.0. CoreAnalyzer2 helps determine which SSD and firmware are most suitable for a customer's application, and SSDWidget 2.0 allows for customers to remotely monitor SSD status in real-time on smartphones or other connected devices, via their private server.





CoreAnalyzer2

CoreAnalyzer is an exclusive, analytic data-behavior technology integrated with Apacer's SSD products. By collecting and analyzing data from a customer's host system, it can help customers analyze their usage behavior so they can choose the best-suited SSD for their application.

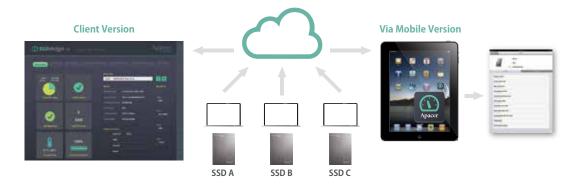




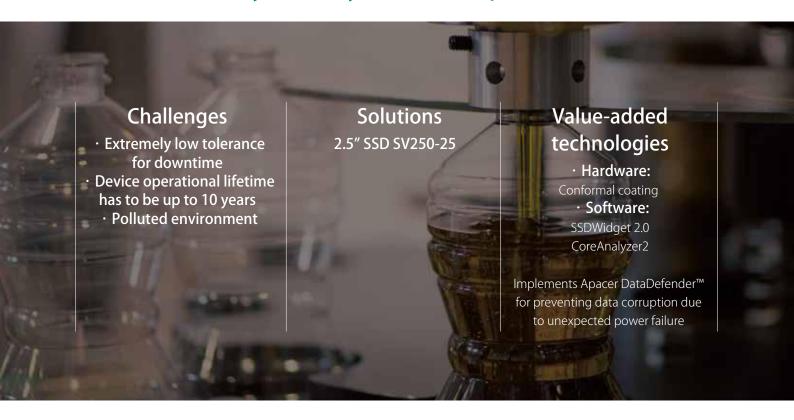
SSDWidget 2.0

Intelligent and comprehensive monitoring and maintaining software

This program features advanced monitoring that allows users to get more detailed read and write records for further use-behavior analysis. The SSD self-test and performance optimization are also included.



Success Story - They Chose Apacer



Introduction

Manufacturers around the world are realizing the advantages of factory automation, and investing R&D resources in developing their strengths in this field. In addition to the obvious cost reductions in manpower, the appeal lies in developing reliable production facilities that can function even in adverse environments. But developing truly independent automated facilities requires components with incredible reliability and robust designs. That's where Apacer enters the picture.



The Customer and the Application

A system integrator based in the Asia-Pacific region approached Apacer for assistance with their latest project. They required an ultra-reliable data storage solution for their latest project, which was a food processing system equipped with SCADA technology.

Challenges

This food processing system had to be able to continuously operate around the clock and had an extremely low tolerance for downtime. Yet it was also designed to have an operational lifetime of up to 10 years, so only the most durable components could be chosen. And due to various platform and module restrictions due to legacy hardware and software, the client was concerned about compatibility issues.

Due to the nature of SCADA operation, dynamic data transmission would be necessary at all hours. The client also predicted that voltage instability might be an issue in some locations in the Asia-Pacific region. With all these challenges in mind, Apacer's team of experienced engineers set to work.

Solutions and Technologies

Apacer's engineering team studied the problem closely and came up with some recommendations for the client. First of all, they recommended the client integrate Apacer's Double-barreled Solution into their system. The SSDWidget2.0 application, which is one of the two key elements of the Double-barreled Solution, would allow operators to determine when an SSD was reaching the end of its operational lifetime, and let them replace it before it ceased to function. This way, downtime would be eliminated and data integrity would be maintained. In fact, Apacer's engineering team carried out some software customizations for this client to ensure there would be no compatibility issues.

In order to prevent data corruption due to unexpected power failure, the Apacer team also recommended that the client adopt Apacer's DataDefender™ technology for the project. This power management system is designed to detect any unexpected drops in voltage and perform a safe shutdown if such an event occurs.

And to allow the system to function in challenging environments, the engineering team finally recommended that the client opt for conformal coating treatments. These would prevent damage that might occur if moisture or detritus (such as food particles) came into contact with sensitive components, helping the client's system remain operational longer.

Results and Benefits:

In the end, the client decided to take all of Apacer's recommendations. This resulted in the creation of a durable, trustworthy food processing system that proved resilient enough to function smoothly even after years of continuous use. The client also let Apacer know that their relationships with their downstream buyers were significantly solidified due to the food processing system's durability and resistance to adverse conditions.

Additional Support



Longevity

Fixed BOM solution, EOL & LTB notice



Strong customization capabilities

Strong HW/FW engineering know-how



Service

Real-time and responsive after-sales service

Apacer's Strengths







Industrial solutions for factory automation applications

Value-added application

Double-barreled Solution

- · CoreAnalyzer2
- · SSDWidget 2.0

Longevity

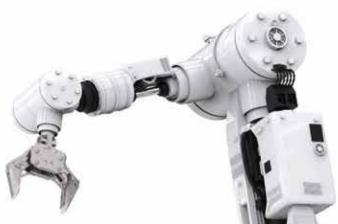
• Fixed BOM support
• Unique S/N for RMA tracking

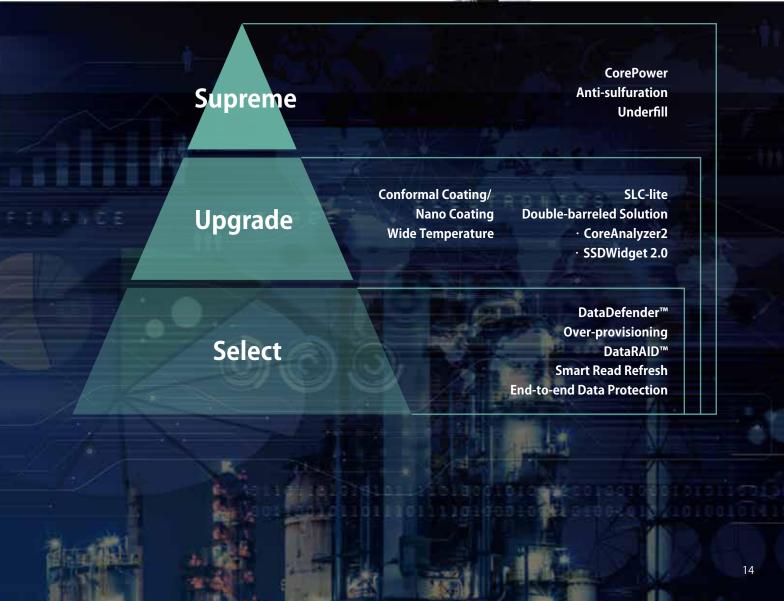
Strong R&D and customization capabilities

Apacer's Premium Package: RoboPro™

A Customized Technology Set for Factory Automation

Factory automation can be an extremely complicated process. With that in mind, Apacer assembled a selection of value-adding technologies into its factory automation technology set, known as RoboPro™. These technologies help deliver the reliability and processing speed that industry leaders demand. RoboPro™ is divided into three levels of sophistication: Select, Upgrade and Supreme, as detailed in the diagram below.





2.5" SATA SSD













| | | 1 | | II III III III | A SECTION | A SECTION AND |
|---|--|--|--|--|--|--|
| Model | SV250-25 | SU210-25 | SM230-25 | SM21P-25 | SM210-25 | SS21P-25 |
| Interface | SATA 3.0 (6Gb/s) | SATA 3.0 (6Gb/s) | SATA 3.1 (6Gb/s) | SATA 3.0 (6Gb/s) | SATA 3.0 (6Gb/s) | SATA 3.0 (6Gb/s) |
| NAND Flash Type | 3D TLC | MLC | MLC | MLC | MLC | SLC |
| Connector | (7+15) pin male | (7+15) pin male | (7+15) pin | (7+15) pin male | (7+15) pin male | (7+15) pin male |
| Form Factor | 2.5" | 2.5" | 2.5" | 2.5" | 2.5" | 2.5" |
| Capacity | 30GB~480GB | 16GB~256GB | With AES 256 support: 32GB~1TB With TCG Opal 2.0 support: 32GB~512GB | 32GB~512GB | 32GB~512GB | 32GB~240GB |
| External DRAM | No | Yes | No | Yes | Yes | Yes |
| EST. Seq R/W Performance (MB/sec) | 560/520 | 545/450 | 530/520 | 505/470 | 510/38 | 550/440 |
| Standard Operating Temperature (°C) | 0 ~ + 70 | 0 ~ + 70 | 0 ~ + 70 | 0 ~ + 70 | 0 ~ + 70 | 0 ~ + 70 |
| Wide Temperature (°C) | -40 ~ + 85 | -40 ~ + 85 | -40 ~ + 85 | -40 ~ + 85 | -40 ~ + 85 | -40 ~ + 85 |
| Storage Temperature (°C) | -40 ~ + 100 | -40 ~ + 100 | -40 ~ + 100 | -40 ~ + 100 | -40 ~ + 100 | -40 ~ + 100 |
| ECC Engine | Low-Density Parity-Check (LDPC) Code | | | Built-in 40-bit per 1K bytes BCH ECC | | |
| IOPS (4K Random Write) | 74K | 80K | 65K | 81K | 79K | 76K |
| Thermal Sensor | Yes | Yes | Yes | Yes | Yes | Yes |
| Shock | | | | nalf sine (compliant ns)/half sine (compli | | |
| Operating Voltage | $5.0 V \pm 5\%$ | $5.0~V\pm5\%$ | $5.0\mathrm{V}\pm5\%$ | $5.0 V \pm 5\%$ | $5.0 V \pm 5\%$ | $5.0\mathrm{V}\pm5\%$ |
| Power Consumption | Active mode: 385 mA / Idle mode: 100 mA | Active mode: 560 mA / Idle mode: 75 mA | Active mode: 500 mA / Idle mode: 95 mA | Active mode: 1100 mA / Idle mode: 120 mA | mA / Idle mode: 75 mA | Active mode: 500 mA / Idle mode: 95 mA |
| Dimension (mm) | 7mm:100.00 x 69.85 x 6.90 9.5mm: 100.00 x 69.85 x 9.3 | 7mm:100.00 x 69.85 x 6.90 9.5mm: 100.00 x 69.85 x 9.3 | 7mm:100.00 x 69.85 x 6.90 9.5mm: 100.00 x 69.85 x 9.3 | 9.5mm: 100.00 x 69.85 x 9.3 | 7mm:100.00 x 69.85 x 6.90 9.5mm: 100.00 x 69.85 x 9.3 | 9.5mm: 100.00 x 69.85 x 9.3 |
| MTBF (hours) | >1,000,000 | >1,000,000 | >1,200,000 | >1,000,000 | >1,000,000 | >2,000,000 |

M.2 2280 & M.2 2242











| | 2 marie 2 | 3 | - | | |
|--|--|--|--|--|---|
| Model | SV250-M280 | SU210-M280 | SS210-M280 | SV250-M242 | SS220-M242 |
| Interface | SATA 3.0 (6Gb/s) | SATA 3.0 (6Gb/s) | SATA 3.0 (6Gb/s) | SATA 3.0 (6Gb/s) | SATA 3.0 (6Gb/s) |
| NAND Flash Type | 3D TLC | MLC | MLC | 3D TLC | SLC |
| Connector | M.2 B & M key | M.2 B & M key | M.2 B & M key | M.2 B & M key | M.2 B & M key |
| Form Factor | M.2 2280 | M.2 2280 | M.2 2280 | M.2 2242 | M.2 2242 |
| Capacity | 30GB~960GB | 32GB ~ 256GB | 16GB~128GB | 30GB~480GB | 1GB~64GB |
| External DRAM | No | Yes | Yes | No | Yes |
| EST. Seq R/W Performance (MB/sec) | 560/525 | 555/465 | 555/445 | 560/520 | 520/455 |
| Standard Operating Temperature (°C) | 0 ~ + 70 | 0 ~ + 70 | 0 ~ + 70 | 0 ~ + 70 | 0 ~ + 70 |
| Wide Temperature (°C) | -40 ~ + 85 | -40 ~ + 85 | -40 ~ + 85 | -40 ~ + 85 | -40 ~ + 85 |
| Storage Temperature (°C) | -40 ~ + 100 | -40 ~ + 100 | -40 ~ + 100 | -40 ~ + 100 | -40 ~ + 100 |
| ECC Engine | Low-Density Parity- Check (LDPC) Code | Built-in up to 72-bit per 1K bytes BCH ECC | Built-in up to 40-bit per 1K bytes BCH ECC | Low-Density Parity- Check (LDPC) Code | Built-in up to 40-bit per 1K bytes BCH ECC |
| IOPS (4K Random Write) | 75K | 78K | 75K | 75K | 80K |
| Thermal Sensor | Yes | Yes | Yes | Yes | Yes |
| Shock | | | /11ms (compliant with 00G/0.5ms (compliant v | | |
| Vibration | | | 2000 Hz/random (com 15 ~ 2000 Hz/sine (con | | |
| Operating Voltage | 3.3 V ± 5% | 3.3 V ± 5% | 3.3 V ± 5% | 3.3 V ± 5% | 3.3 V ± 5% |
| Power Consumption | Active mode:455 mA / Idle mode: 80 mA | | Active mode: 705 mA & Idle mode: 155 mA | | Active mode: 570mA & Idle mode: 85 mA |
| Dimension (mm) | Single side: 80.00 x 22.00 x 2.38 Double side: 80.00 x 22.00 x 3.88 | Single side: 80.00 x 22.00 x 2.23 Double side: 80.00 x 22.00 x 3.58 | Single side: 80.00 x 22.00 x 2.23 Double side: 80.00 x 22.00 x 3.58 | 42.00 x 22.00 x 3.80 | 42 x 22 x 3.6 |
| MTBF (hours) | >1,000,000 | >1,000,000 | >1,000,000 | >1,000,000 | >2,000,000 |

mSATA/ mSATA mini









| COLUMN COLUMN | - | THE REAL PROPERTY. | Jan to Lead. |
|---|--|--|--|
| SV250-300 | SV250-300B | SU210-300 | SS210-300 |
| SATA 3.0 (6Gb/s) | SATA 3.0 (6Gb/s) | SATA 3.0 (6Gb/s) | SATA 3.0 (6Gb/s) |
| 3D TLC | 3D TLC | MLC | SLC |
| 52 pin male | 52 pin male | 52 pin male | 52 pin male |
| MO300 | MO300B | JEDEC MO-300 | JEDEC MO-300 |
| 30~480GB | 30~240GB | 8GB~256GB | 2GB~128GB |
| NO | NO | Yes | Yes |
| 560/515 | 560/510 | 555/465 | 525/445 |
| 0 ~ + 70 | 0~+70 | 0 ~ + 70 | 0 ~ + 70 |
| -40 ~ + 85 | -40 ~ + 85 | -40~ + 85 | -40 ~ + 85 |
| -40 ~ + 100 | -40 ~ + 100 | -40~ + 100 | -40 ~ + 100 |
| Low-Density Parity-Check (LDPC) Code | Low-Density Parity-Check (LDPC) Code | Built-in 40-bit per 1K bytes BCH ECC | Built-in 40-bit per 1K bytes BCH ECC |
| 75K | 74K | - | 76K |
| Yes | Yes | Yes | Yes |
| | | | |
| Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 15G, 10 ~ 2000 Hz/sine | | (compliant with Non-operation: 4.02 G | , 20~2000 Hz/random I MIL-STD-810G) rms, 15 ~ 2000 Hz/sine I MIL-STD-810G) |
| $3.3~\text{V}\pm5\%$ | $3.3~\text{V}\pm5\%$ | $3.3 V \pm 5\%$ | $3.3~\text{V}\pm5\%$ |
| Active mode: 425 mA & Idle mode: 115 mA | Active mode: 430 mA & Idle mode: 125 mA | Active mode: 760 mA / Idle mode: 180 mA | Active mode: 685 mA / Idle mode: 180 mA |
| 50.80 x 29.85 x 4.85 | 29.85 x 26.80 x 3.85 | Without housing: 50.8 x 29.85 x 3.8 | Without housing: 50.8 x 29.85 x 3.8 |
| >1,000,000 | >1,000,000 | >1,000,000 | >2,000,000 |
| | SATA 3.0 (6Gb/s) 3D TLC 52 pin male MO300 30~480GB NO 560/515 $0 \sim + 70$ $-40 \sim + 85$ $-40 \sim + 100$ Low-Density Parity-Check (LDPC) Code 75K Yes Operation: 7.69 Grms, (compliant with Non-operation: 15G) 3.3 V \pm 5% Active mode: 425 mA & Idle mode: 115 mA 50.80 x 29.85 x 4.85 | SATA 3.0 (6Gb/s) SATA 3.0 (6Gb/s) 3D TLC 3D TLC 52 pin male 52 pin male MO300 MO300B 30~480GB 30~240GB NO NO 560/515 560/510 0~+70 0~+70 -40~+85 -40~+85 -40~+100 -40~+100 Low-Density Parity-Check (LDPC) Code Low-Density Parity-Check (LDPC) Code 75K 74K Yes Yes Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 15G, 10~2000 Hz/sine 3.3 V ± 5% 3.3 V ± 5% Active mode: 425 mA & Idle mode: 125 mA Active mode: 430 mA & Idle mode: 125 mA 50.80 x 29.85 x 4.85 29.85 x 26.80 x 3.85 | SATA 3.0 (6Gb/s) SATA 3.0 (6Gb/s) SATA 3.0 (6Gb/s) 3D TLC 3D TLC MLC 52 pin male 52 pin male 52 pin male MO300 MO300B JEDEC MO-300 30~480GB 30~240GB 8GB~256GB NO NO Yes 560/515 560/510 555/465 0~+70 0~+70 0~+70 -40~+85 -40~+85 -40~+85 -40~+100 -40~+100 -40~+100 Low-Density Parity-Check (LDPC) Code Low-Density Parity-Check Built-in 40-bit per 1K bytes BCH ECC 75K 74K - Yes Yes Ves Yes Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 150G, 0.5ms Operation: 7.69 Grms, 20~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 4.02 G (compliant with MIL-STD-810G) Non-operation: 15G, 10~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 150G (compliant with MIL-STD-810G) Non-operation: 15G, 10~2000 Hz/random (compliant with MIL-STD-810G) Non-operation: 150G (compliant with MIL-STD-810G) Non-operation: 15G, 10~2000 Hz/random (compliant with MIL-STD-810G) Non-oper |

CF/ CFast Cards











| Model | Industrial CF6A-SL | Industrial CF6A-M | Industrial CF6A | SM230-CFast | SS220-CFast |
|---|---|---|---|---|---|
| Interface | PC Card Memory Mode; PC Card I/O Mode; True IDE Mode | PC Card Memory Mode; PC Card I/O Mode; True IDE Mode | PC Card Memory Mode; PC Card I/O Mode; True IDE Mode | SATA 3.0 (6Gb/s) | SATA 3.0 (6Gb/s) |
| Connector | 50-pin | 50-pin | 50-pin | 7 + 17 pin female connector | (7+17) pin male |
| Form Factor | CompactFlash Type I | CompactFlash Type I | CompactFlash Type I | CFast | CFast |
| NAND Flash Type | MLC | MLC | SLC | MLC | SLC |
| Capacity | 4GB~32GB | 8GB~64GB | 256MB~32GB | 8GB~256GB | 4GB~64GB |
| External DRAM | - | - | - | No | Yes |
| EST. Seq R/W Performance (MB/sec) | 115/80 | 115/75 | 60/65 | 560/470 | 555/445 |
| Standard Operating Temperature (°C) | 0 ~ + 70 | 0 ~ + 70 | 0 ~ + 70 | 0 ~ + 70 | 0 ~ + 70 |
| Wide Temperature (°C) | -40 ~ + 85 | -40 ~ + 85 | -40 ~ + 85 | -40 ~ + 85 | -40 ~ + 85 |
| Storage Temperature (°C) | -40 ~ + 100 | -40 ~ + 100 | -40 ~ + 100 | -40 ~ + 100 | -40 ~ + 100 |
| ECC Engine | Built-in 72-bit per 1K bytes BCH ECC | Built-in 72-bit per 1K bytes BCH ECC | Built-in 72-bit per 1K bytes BCH ECC | Built-in up to 72-bit per 1K bytes BCH ECC | Built-in 40-bit per 1K bytes BCH ECC |
| IOPS (4K Random Write) | 157 | 231 | 188 | 40K | 80K |
| H/W Write Protect | Yes | Yes | Yes | YES | Yes |
| Thermal Sensor | - | - | - | YES | - |
| Shock | | | /11ms (compliant with 00G/0.5ms (compliant) | | |
| Vibration | Оре | eration: 7.69 Grms, 20~ | 2000 Hz/random (com | pliant with MIL-STD-81 | 0G) |
| Power Consumption | Operating Voltage:3.3V - Active mode: 235mA - Standby mode: 10mA Operating Voltage:5.0V - Active mode: 245mA - Standby mode: 10mA | Operating Voltage:3.3V – Active mode: 255mA – Standby mode: 10mA Operating Voltage:5.0V – Active mode: 260mA – Standby mode: 10mA | Operating Voltage:3.3V - Active mode: 165mA - Standby mode: 10mA Operating Voltage:5.0V - Active mode: 230mA - Standby mode: 10mA | Active mode: 645 mA / Idle mode: 135 mA | |
| Dimension (mm) | 36.4 x 42.8 x 3.3 | 36.4 x 42.8 x 3.3 | 36.4 x 42.8 x 3.3 | 42.80 x 36.45x 3.60 | 42.8 x 36.4 x 3.6 |
| MTBF (hours) | >1,000,000 | >1,000,000 | >2,000,000 | >1,000,000 | >2,000,000 |

UDM/ USB drive/ microSD













| | 老 MODELLAS | 200 | | | | |
|---|---|---|--|--|---|---|
| Model | UDM2A-M (Type C) | UDM2A (Type D) | EH353-M | EH353 | CV110-MSD | Industrial microSD R1 |
| Interface | USB 2.0 | USB 2.0 | USB 3.0 | USB 3.0 | SD4.0 | SD3.0 |
| Connector | 10 pin USB(2x5) female header in 2.54mm | 10 pin USB(2x5) female header in 2.54mm | USB 3.0 A Type Plug | USB 3.0 A Type Plug | - | - |
| Form Factor | USB disk module | USB disk module | USB flash drive | USB flash drive | microSD | microSD |
| NAND Flash Type | MLC | SLC | MLC | SLC | 3D TLC | SLC |
| Capacity | 8G~128G | 256MB~32G | 8GB~128GB | 256MB~32GB | SDHC:32GB~256GB | SD:GB~2GB; SDHC::4~8GB |
| EST. Seq R/W Performance (MB/sec) | 44/43 | 44/41 | 205/95 | 80/70 | 90/34 | 34/28 |
| ECC Engine | Built-in 72-bit per 1K bytes BCH ECC | Built-in 72-bit per 1K bytes BCH ECC | Built-in 39-bit per 1K bytes BCH ECC | Built-in 39-bit per 1K bytes BCH ECC | Built-in advanced ECC algorithm | Built-in 43-bit per 1K bytes BCH ECC |
| IOPS (4K Random Write) | 190 | 105 | - | - | 1300 | - |
| Standard Operating Temperature (°C) | 0~+70 | 0 ~ + 70 | 0 ~ + 70 | 0~+70 | -25 ~ + 85 | - |
| Wide Temperature (°C) | -40 ~ + 85 | -40 ~ + 85 | -40 ~ + 85 | -40 ~ + 85 | -40 ~ + 85 | -40 ~ + 85 |
| Storage Temperature (°C) | -40 ~ + 100 | -40 ~ + 100 | -40 ~ + 100 | -40 ~ + 100 | -40 ~ + 85 | -40 ~ + 100 |
| H/W Write Protect | No | No | - | - | - | - |
| Screw Hole | Yes | Yes | - | - | - | - |
| Shock | (Non | Operation: Accelera -operation: Acceler | tion, 50(G)/11(ms)/h ation,1,500(G)/0.5(n | nalf sine (compliant ns)/half sine (compl | with MIL-STD-2020 iant with MIL-STD-8 | 5) 883K) |
| Vibration | N | | | ındom (compliant v /random (complian | | |
| Operating Voltage | 5V ± 5% | 5V ± 5% | 5.0 V ± 5% | 5.0 V ± 5% | 2.7V ~ 3.6V | 3.3 V ± 5% |
| Power Consumption | Active mode: 125 mA & Idle mode:50 mA | Active mode: 110 mA & Idle mode:45 mA | Active mode: 275 mA & Idle mode: 80 mA | Active mode: 225 mA & Idle mode: 65 mA | Active mode: 105 mA & Idle mode: 185 uA | Active mode: 115 mA & Idle mode: 265 uA |
| Dimension (mm) | 37.8 x 26.65 x 10.76 | 36.8 x 26.65 x 5 | 59 x 18.4 x 9.1 | 59 x 18.4 x 9.1 | 15x11x1 | 15x11x1 |
| MTBF (hours) | >1,000,000 | >2,000,000 | >1,000,000 | >2,000,000 | >3,000,000 | >3,000,000 |
| | | | | | | |

Wide Temp. ECC SODIMM





| Model | DDR4 Wide Temp. ECC SODIMM | DDR3 Wide Temp. ECC SODIMM | |
|-----------------------|---|---|--|
| Module Type | Wide Temperature ECC SODIMM | Wide Temperature ECC SODIMM | |
| Memory Technology | DDR4 | DDR3 | |
| Frequency | 2133/2400/2666 | 1066/1333/1600 | |
| Density | 4G/8G/16G | 2G/4G/8G | |
| Voltage | 1.2v | 1.5v/1.35v | |
| Pin Count | 260-Pin | 204-Pin | |
| Width | 72-Bit | 72-Bit | |
| PCB Height | 1.18" | 1.18" | |
| Operation Temperature | TC=-40°C to 85°C | TC=-40°C to 85°C | |
| Value-added | ₩ Wide Temperature Sensor Gad Finger Uniderfill Caucing | Wide Temperature Sensor Gold Finger Underfill Coating | |

Wide Temp. SODIMM









| | | The second secon | San Land | SAMPLE SAMPLE STATE OF THE PERSON. |
|-----------------------|----------------------------|--|----------------------------|------------------------------------|
| Model | DDR4 Wide Temp. SODIMM | DDR3 Wide Temp. SODIMM | DDR2 Wide Temp. SODIMM | DDR Wide Temp. SODIMM |
| Module Type | Wide Temperature SODIMM | Wide Temperature SODIMM | Wide Temperature SODIMM | Wide Temperature SODIMM |
| Memory Technology | DDR4 | DDR3 | DDR2 | DDR |
| Frequency | 2133/2400/2666 | 1066/1333/1600 | 533/667/800 | 266/333/400 |
| Density | 4G/8G/16G | 1G/2G/4G/8G | 512M/1G/2G | 512M/1G |
| Voltage | 1.2v | 1.5v/1.35v | 1.8v | 2.5v/2.6v |
| Pin Count | 260-Pin | 204-Pin | 200-Pin | 200-Pin |
| Width | 64-Bit | 64-Bit | 64-Bit | 64-Bit |
| PCB Height | 1.18" | 1.18" | 1.18" | 1.25" |
| Operation Temperature | TC=-40°C to 85°C | TC=-40°C to 85°C | TC=-40°C to 85°C | TA=-40°C to 85°C |
| Value-added | 30µ | <u></u> 30µ <u></u> <u></u> <u></u> <u></u> <u></u> <u></u> <u> </u> <u> </u> | № 30µ № | <u> </u> |

Basifreer Underful Conternal Temperature Basifreer Underful Cooking Temperature Underful Cooking Temperature

VLP SODIMM & VLP ECC SODIMM





| Model | DDR4 VLP SODIMM | DDR4 VLP ECC SODIMM |
|-----------------------|------------------------------|--|
| Module Type | VLP SODIMM | VLP ECC SODIMM |
| Memory Technology | DDR4 | DDR4 |
| Frequency | 2133/2400/2666 | 2133/2400/2666 |
| Density | 4G/8G | 4G/8G |
| Voltage | 1.2v | 1.2v |
| Pin Count | 260-Pin | 260-Pin |
| Width | 64-Bit | 72-Bit |
| PCB Height | 0.71" | 0.7" |
| Operation Temperature | TC=-0°C to 85°C | TC=-0°C to 85°C |
| Value-added | 30µ Linderfill Control Coord | Tenencal SOµ Dindertil Concord Concord |

Anti-sulfuration SODIMM





| Model | DDR4 Anti-sulfuration SODIMM | DDR3 Anti-sulfuration SODIMM |
|--------------------------|--------------------------------|--------------------------------|
| Module Type | Anti-sulfuration SODIMM | Anti-sulfuration SODIMM |
| Memory Technology | DDR4 | DDR3 |
| Frequency | 2133/2400/2666 | 1066/1333/1600 |
| Density | 4G/8G/16G | 1G/2G/4G/8G |
| Voltage | 1.2v | 1.35v/1.5v |
| Pin Count | 260-Pin | 204-Pin |
| Width | 64-Bit | 64-Bit |
| PCB Height | 1.18" | 1.18" |
| Operation Temperature | TC=0°C to 85°C / -40°C to 85°C | TC=0°C to 85°C / -40°C to 85°C |
| W.L II. I | 30. ¥ | 20. |

Value-added















About Apacer

Apacer is a global leader in digital storage solutions devoted to innovative storage technology and services. After 20 years in the industry, we remain dedicated to our belief in "persistence in doing the right things." Our core values, as always, continue to revolve around reliability and innovation.

The company focuses on embedded applications for a variety of vertical markets, including military, medical, gaming, and industrial, and has become an integration expert in digital storage, innovative applications, and value-added services. Apacer is known for its advanced technologies and product quality and was ranked by Gartner as the top industrial SSD supplier for five consecutive years, from 2012 to 2016. In addition, Apacer is committed to making a positive impact on societal issues and has joined the **Responsible Business Alliance (RBA)**, which is formerly known as Electronic Industry Citizenship Coalition (EICC), a coalition promoting **corporate social responsibility (CSR)** within the global electronics supply chain. We believe that the success of a corporation is marked not by profit but by how we benefit others, whether by caring for the environment or making contributions to society.



Compliance and Associations



